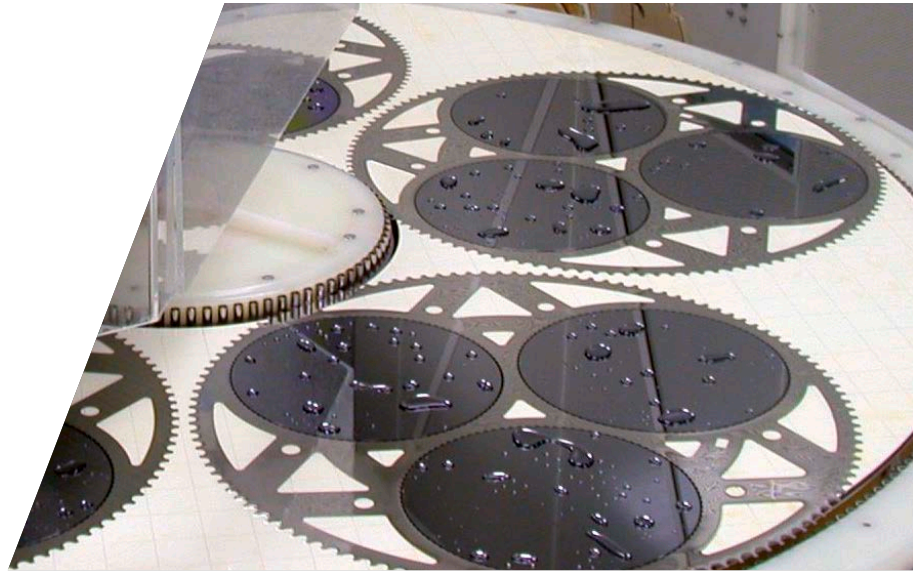






AC microLine® 2000-P⁴

PRIME WAFER DOUBLE-SIDE POLISHING SYSTEM



15 WAFER/BATCH 300 mm WAFER

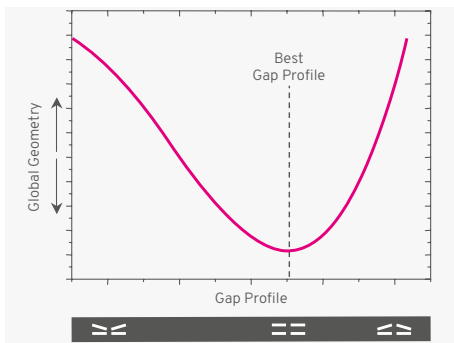
THE MOST COMPREHENSIVE SOLUTION

-  Unique LPAC
(Lower Platen Adaptive Control) System (patent pending)
-  Unique and patented UPAC
(Upper Platen Adaptive Control) System
-  3 Gap Sensors
-  Benchmark in precision, quality, efficiency,
and cost of ownership

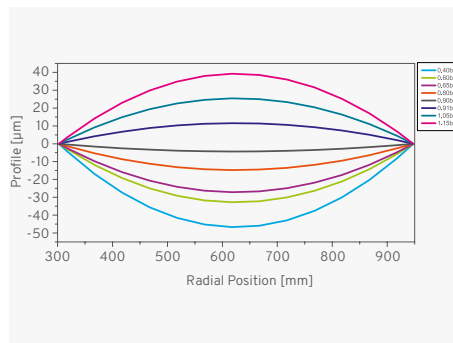
PUSHING THE LIMITS

HIGHLIGHTS AC microLine® 2000-P⁴

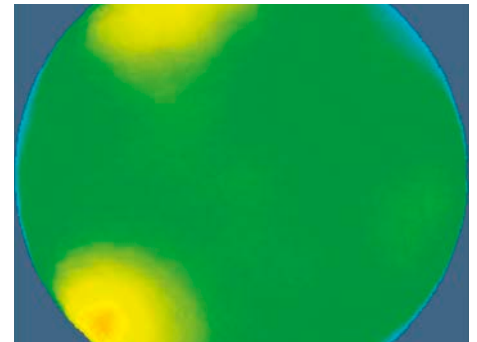
- ☑ Unique and patented UPAC (Upper Platen Adaptive Control) System
- ☑ Unique LPAC (Lower Platen Adaptive Control) System (patent pending)
- ☑ Monitoring of the cooling lubricant flow rate
- ☑ Loop control
- ☑ First-Class customer support for the highest machine availability and productivity
- ☑ Integrated high precision interferometric device for in-situ measurement of the wafer thickness
- ☑ High-Pressure Conditioner
- ☑ Slurry Recycling Station
- ☑ Slurry Pressure Distribution
- ☑ Integrated Process Data Recording (DataCare®)
- ☑ Industry 4.0
- ☑ Touch Screen



The importance of the gap – Perfect wafer flatness requires gap adjustment



LPAC System – Radial Measurement



GBIR < 100 nm / SBIR < 40 nm
SFQR < 20 nm / ESFQR < 60 nm

TECHNICAL DATA	AC microLine® 2000-P ⁴
Wheel diameter [mm]	1935
Ring width [mm]	686
Max. load pressure [daN]	4000
Upper / lower drive power [kW]	46
Upper / lower drive speed [rpm]	0–40
Center drive power [kW]	7.5
Center drive speed [rpm]	0–50
Outer drive power [kW]	9.5
Outer drive speed [rpm]	0–7.5
Working wheel cooling	Labyrinth
Dimensions [H × W × D] [mm]	3000 × 4200 × 3900
Weight [kg]	21000
Load capacity	
300 mm [12"] Wafer	15 pieces
200 mm [8"] Wafer	30 pieces

GET IN TOUCH WITH US TODAY
TOGETHER WE WILL FIND A SOLUTION
FOR YOUR REQUIREMENTS

LAPMASTER WOLTERS GMBH

Phone: +49 4331 458 0

ac@lapmaster-wolters.de

www.lapmaster-wolters.de